

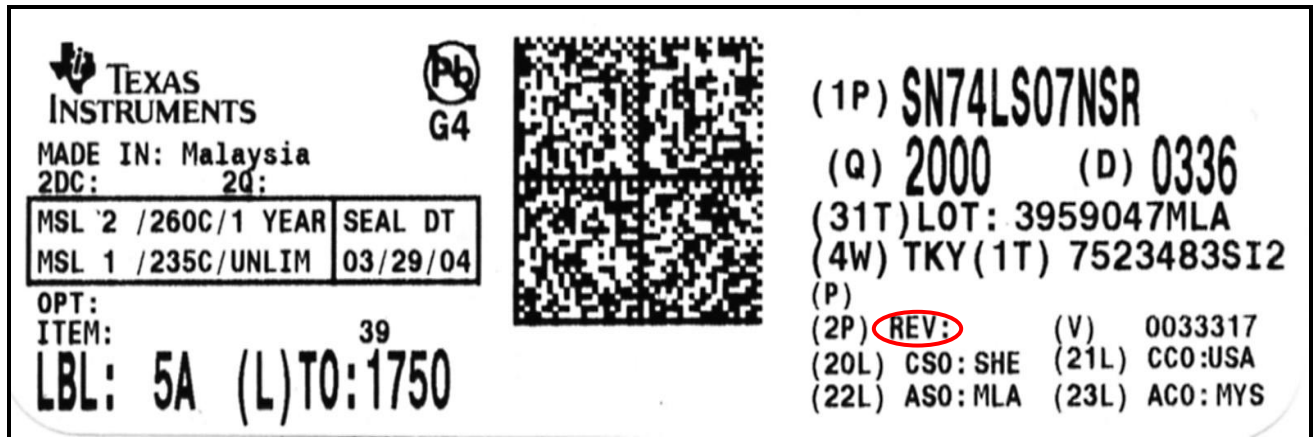
PCN Number:	20140414001B			PCN Date:	4/14/2014				
Title:	Design Revision (for Select TMP708/709 Devices)								
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept:	Quality Services				
Proposed 1st Ship Date:	10/14/2014 7/14/2014		Estimated Sample Availability:	Date provided at sample request					
Change Type:									
<input checked="" type="checkbox"/>	Design								
PCN Details									
Description of Change:									
<p>The purpose of Revision B is to correct the 1st Ship Date above. This PCN will expire on 7/14/2014 and the change may be implemented. We apologize for any confusion this may have caused.</p> <p>This notification is to inform of a design revision for select TMP708/709 devices. This design change does not affect the device's guaranteed datasheet specifications or electrical performance. The affected devices are listed in the "Product Affected" section.</p> <p>The table below describes changes that were made:</p> <table border="1" style="width: 100%;"> <thead> <tr> <th style="text-align: center;">Description of Change</th> <th style="text-align: center;">Benefit of Change</th> </tr> </thead> <tbody> <tr> <td>Revision of die to eliminate startup issue.</td> <td>Improve reliability</td> </tr> </tbody> </table>						Description of Change	Benefit of Change	Revision of die to eliminate startup issue.	Improve reliability
Description of Change	Benefit of Change								
Revision of die to eliminate startup issue.	Improve reliability								
Reason for Change:									
Improve reliability									
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):									
None									

Changes to product identification resulting from this PCN:

Die Rev designator will change as shown in table & sample label below:

Current	New
Die Rev [2P] A	Die Rev [2P] B

Sample product shipping label to indicate die rev location (**not actual product label**)



Product Affected:

Refer to Page 2 for affected products.

Qualification Data: Approved 4/10/2014

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Device: TMP708AIDBV

Package/Die Construction Details

Assembly Site:	NFME	# Pins-Designator, Family:	5-DBV, SOT
Fab Process:	50HPA07	Die Revision:	B

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Characterization, side by side	Per Datasheet Parameters	Pass
ESD HBM	1000V	3/0
ESD CDM	250V	3/0
Latch-up	Per JESD78	6/0

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or to your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com